

A WIRE BONDING METHOD

BACKGROUND OF THE INVENTION

1. Field of the Invention

The present invention relates to a wire bonding method that performs wire bonding between two conductors.

2. Prior Art

Japanese Patent Application Laid-Open (Kokai) Nos. 10-112471 and 2002-280410 disclose wire bonding methods that connect a wire between a first conductor and a bump on a second conductor after such a bump is formed on the second conductor.

In Japanese Patent Application Laid-Open (Kokai) No. 10-112471, a bump is formed by performing ball bonding on the second conductor; and after wedge bonding is performed on the opposite side of the bump from the first conductor, primary bonding is performed on the first conductor. Then, the wire is looped from the first conductor side with respect to the bump, and secondary bonding is performed on the bump.

In Japanese Patent Application Laid-Open (Kokai) No 2002-280410, after a bump has been formed by performing, using a bonding wire, ball bonding on the second conductor, the capillary is moved upward, and this capillary is then moved to a position that is on the opposite side from the first conductor. The capillary is then again moved downward so that an inclined wedge is formed on the bump, after which primary bonding is performed on the first conductor, the wire is looped from the first conductor side with respect to the bump, and secondary bonding is performed on the inclined wedge that is on the upper part of the bump.

The method of the Japanese Patent Application Laid-Open (Kokai) No. 10-112471 has problems. It involves wedge bonding and joining of the wire that takes place after bump formation; in other words, it involves joining of curved surfaces to each other; as a result, in cases where deviation of the joining position occurs, wire bending occurs as a result, and adjacent wires come into contact with each other. Furthermore, although the generation of a wire tail can be suppressed by forming the wedge bonding after bump formation in a shape

that is bent toward the rear, a sufficient inclination and flat surface cannot be ensured in the joining of the wire and bump. Accordingly, contact between the wire and circuit board and contact between the wire and wiring following the joining of the bump and wire cannot be prevented.

In the Japanese Patent Application Laid-Open (Kokai) No 2002-280410, a bump is formed by performing ball bonding on the wiring part, and the capillary is then raised and moved from the center of the bump into the opposite direction from the first conductor, after which the capillary is again pressed downward so that an inclined wedge is formed on the bump by the outer wall surface of the capillary, and secondary bonding is performed on the inclined wedge. Thus, problems seen in Japanese Patent Application Laid-Open (Kokai) No. 10-112471 does not occur in the method of the Japanese Patent Application Laid-Open (Kokai) No. 2002-280410.

In the method of Japanese Patent Application Laid-Open (Kokai) No. 2002-280410, the capillary is pressed down to the bump so as to form an inclined wedge on the bump using the outer wall surface of the capillary. Thus, an inclination and flat surface of the bump are wider than those in the method of Japanese Patent Application Laid-Open (Kokai) No. 10-112471. However, in Japanese Patent Application Laid-Open (Kokai) No. 10-112471, the inclined wedge is formed on the bump after the capillary has been moved upward to the wire portion following the bump formation; accordingly, a more sufficiently wide flat surface is not formed. A narrow surface area on the inclined wedge causes unreliable bonding, and the secondarily bonded wire can be easily bent. Thus, a stable wire loop is not obtainable.

SUMMARY OF THE INVENTION

The object of the present invention is to provide a wire bonding method which that forms a sufficiently wide inclined wedge on a bump, thus obtaining an improved reliability of the bonding joint and a stable wire loop.

The above object is accomplished by unique steps of the present invention for a wire bonding method in which primary bonding is performed on a first conductor, and then secondary bonding is performed on a second conductor, thus wire-bonding between the first conductor and second conductor; and in the present invention, the method comprises the steps

of: forming a bump by performing ball bonding by wire on the second conductor, raising a capillary to a height that is equal to or lower than the height of a ball portion that rises into a through-hole of the capillary during formation of the bump, moving the capillary in a direction that is opposite from the first conductor, lowering the capillary so as to form an inclined wedge on the bump, cutting the wire, performing the primary bonding on the first conductor, and making a loop with the wire with respect to the bump from the first conductor, thus performing the secondary bonding on the inclined wedge on the bump.

BRIEF DESCRIPTION OF THE DRAWINGS

Figure 1 shows the sequential steps (a) through (f) of the wire bonding method according to one embodiment of the present invention;

Figure 2 shows the sequential steps (a) and (b), the step (a) in Figure 2 following the last step (f) shown in Figure 1; and

Figure 3 is a diagram that shows another example of wire bonding between a die and wiring using the wire bonding method of the embodiment of the present invention.

DETAILED DESCRIPTION OF THE INVENTION

The wire bonding method of one embodiment of the present invention will be described below with reference to Figures 1 and Figure 2. In Figure 2, the step (b) shows the completed state of wire bonding between a die and wiring performed using the wire bonding method of one embodiment of the present invention.

As seen from the step (b) in Figure 2, a die 2 on which a pad 2a is formed is mounted on a circuit board 1 which is a substrate such as a ceramic substrate, printed substrate, etc. or is a lead frame, etc. Wiring 3 is formed on the circuit board 1. A bump 10 is formed on the wiring 3, and a wire 4 is connected between the pad 2a and bump 10. The reference numeral 5 is a capillary through which the wire 4 passes.

The wire bonding shown in completed step (b) in Figure 2 is obtained by the steps described below.

First, as shown in step (a) of Figure 1, a ball 4a is formed by an electric torch (not shown) on the tip end of the wire 4 that passes through the through-hole 5a of the capillary 5.

Next, in step (b), the capillary 5 is lowered and ball bonding is performed on the wiring 3. As a result, a portion of the ball 4a rises into the interior of the through-hole 5a, so that a hole portion 11 is formed on the bump 10.

Then, in step (c), the capillary 5 is raised so that the edge 5b of the lower end of the capillary 5 is positioned at a level equal to or lower than the height of the hole portion 11.

Next, in step (d) of Figure 1, the capillary 5 is moved in the opposite direction from the pad 2a side (see the (b) of Figure 2).

Then, in step (e), the capillary 5 is lowered so that an inclined wedge 12 is formed on the bump 10 by the lower end surface of the capillary 5, after which the capillary 5 is raised and the wire 4 is cut. Since the capillary 5 is thus lowered to form an inclined wedge 12 on the surface of the bump 10 after the hole portion 11 has been pushed in the lateral direction by the edge 5b of the capillary 5, an inclined wedge 12 with a more sufficiently wide surface area and a flat surface is formed.

Next, in step (f), a ball 4b is formed on the tip end of the wire 4 by an electric torch.

Then, in step (a) shown in Figure 2, the capillary 5 is positioned on the pad 2a of the die 2, and primary bonding is performed.

Then in step (b) shown in Figure 2, the wire 4 is looped so that the wire 4 is positioned on the upper part of the inclined wedge 12 of the bump 10, and the wire 4 is secondarily bonded to the inclined wedge 12, after which the wire 4 is cut.

Figure 3 shows another example of the conditions of wire bonding between a die and wiring using the wire bonding method according to the embodiment of the present invention.

In the embodiment described above, a bump 10 is formed on the wiring 3, the primary bonding is performed on the pad 2a, and the secondary bonding is performed on the inclined wedge 12 on the bump 10.

In the embodiment of Figure 3, a bump 10 is formed on the pad 2a by the steps (a) through (e) shown in Figure 1, and the inclined wedge 12 on the bump 10 is formed on the opposite side from the side of the wiring 3.

Then, primary bonding is performed on the wiring 3 by the steps (a) and (b) shown in Figure 2, after which secondary bonding is performed on the inclined wedge 12 on the bump 10, and then the wire 4 is cut.

In other words, in the case of the steps (a) of Figure 1 through step (b) in Figure 2, the pad 2a is the first conductor, and the wiring 3 is the second conductor. In the case of Figure 3, the wiring 3 is the first conductor, and the pad 2a is the second conductor.

As seen from the above, the present invention is for a wire bonding method in which primary bonding is performed on a first conductor, and then secondary bonding is performed on a second conductor, thus wire-bonding between the first conductor and second conductor; and the present invention comprises the steps of: forming a bump by performing ball bonding by wire on the second conductor, raising a capillary to a height that is equal to or lower than the height of a ball portion that rises into a through-hole of the capillary during formation of the bump, moving the capillary in a direction that is opposite from the first conductor, lowering the capillary so as to form an inclined wedge on the bump, cutting the wire, performing the primary bonding on the first conductor, and making a loop with the wire with respect to the bump from the first conductor, thus performing the secondary bonding on the inclined wedge on the bump. Accordingly, an inclined wedge with a more sufficiently wide area is formed on the bump, so that an improvement in the reliability of the bonding joint and a stable wire loop is assured.